

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Lopatin et al.

Title: METHOD OF USING TERNARY COPPER ALLOY TO
OBTAIN A LOW RESISTANCE AND LARGE GRAIN SIZE
INTERCONNECT

Appl. No.: 09/994,395

Filing Date: 11/26/2001

Examiner: Ori Nadav

Art Unit: 2811

Confirmation Number: 7882

AMENDMENT AND REPLY UNDER 37 CFR 1.116

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Commissioner for Patents
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This communication is responsive to the Decision on Appeal, dated January 27, 2009, concerning the above-referenced patent application.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this document.

Remarks/Arguments begin on page 6 of this document.

Please amend the application as follows: